

English ▼

PRODUCTS APPLICATIONS DESIGN SUPPORT SAMPLE AND BUY ABOUT US CONTACT US MYMICROCHIP LOGIN

more...

Product Change Notification - RMES-10NGWL694 (Printer Friendly)

Date:

08 May 2017

Product Category:

Capacitive Touch Sensors; 8-bit PIC Microcontrollers

Notification subject:

CCB 2913 Initial Notice: Qualification of MTAI as an additional assembly site for selected Atmel products available in 32L TQFP (7x7x1 mm) package using CuPdAu bond wire.

Notification text:

PCN Status:

Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as an additional assembly site for selected Atmel products available in 32L TQFP (7x7x1 mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at LPI, ANAK (ATK) or ANAP (ATP) using gold (Au) or palladium coated copper (PdCu) bond wire.

Post Change:

Assembled at LPI, ANAK (ATK), ANAP (ATP) using gold (Au) or palladium coated copper (PdCu) bond wire or Assembled at MTAI using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

		Pre Change		Post Change						
Assembly Site	LPI	ANAK	ANAP	LPI	ANAK	ANAP	MTAI			
Lead frame material	C7025	CDA194	CDA194	C7025 CDA194		CDA194	C7025			
Wire material	Au or PdCu	Au or PdCu	Au or PdCu	Au or PdCu	Au or PdCu	Au or PdCu	CuPdAu			
Die attach material	CRM1033BF	3230	3230	CRM1033BF	3230	3230	3280			
Mold compound material		G700			G700					

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MTAI as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	May 2017				->	August 2017					
Workweek	18	19	20	21	22		31	32	33	34	35
Initial PCN Issue Date	Χ										
Qual Report Availability										Χ	
Final PCN Issue Date										X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

May 3, 2017: Issued initial notification.

May 8, 2017: Re-issued the initial notification to notify all affected customers.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-10NGWL694_Affected_CPN.pdf PCN_RMES-10NGWL694_Qual_Plan.pdf PCN_RMES-10NGWL694_Affected_CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."













Products | Applications | Design Support | Training | Sample And Buy | About Us | Contact Us | Legal | Investors | Careers | Support

©Copyright 1998-2017 Microchip Technology Inc. All rights reserved.